



#6 H/W  
Docket No.: M1071.1453/P1453 1-2903

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Haruhiko Ikeda

Application No.: 09/927,053

Group Art Unit: 1733

Filed: August 9, 2001

Examiner: Not Yet Assigned

For: METHOD OF BONDING A  
CONDUCTIVE ADHESIVE AND AN  
ELECTRODE, AND A BONDED  
ELECTRODE OBTAINED THEREBY

CHANGE OF CORRESPONDENCE ADDRESS

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In accordance with the Manual of Patent Examining Procedures, Section 601.03, please change the mailing address for all correspondence in the above-identified patent application to:

Steven I. Weisburd  
DICKSTEIN SHAPIRO MORIN & OSHINSKY LLP  
1177 Avenue of the Americas  
41st Floor  
New York, New York 10036-2714  
(212) 835-1400

Please direct all further communications to the above-identified firm.

Dated: January 14, 2003

Respectfully submitted,

By Steven I. Weisburd  
Steven I. Weisburd  
Registration No.: 27,409  
1177 Avenue of the Americas  
41st Floor  
New York, New York 10036-2714  
(212) 835-1400  
Attorneys for Applicant

RECEIVED  
JAN 27 2003  
TC 1700